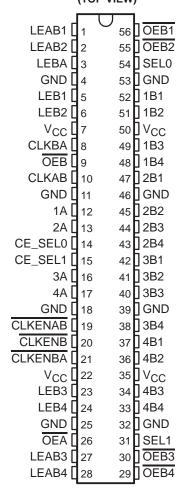
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- Members of the Texas Instruments
 Widebus™ Family
- B-Port Outputs Have Equivalent 25- Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABTH162460 are 4-bit to 1-bit multiplexed registered transceivers used in applications where four separate data paths must be multiplexed onto or demultiplexed from a single data path. Typical applications include multiplexing and/or demultiplexing of address and data information in microprocessor or bus-interface applications. This device also is useful in memory-interleaving applications.

SN54ABTH162460 . . . WD PACKAGE SN74ABTH162460 . . . DL PACKAGE (TOP VIEW)



Five 4-bit I/O ports (1A-4A, 1B1-4, 2B1-4, 3B1-4, and 4B1-4) are available for address and/or data transfer. The output-enable (OEB, OEB1-OEB4, and OEA) inputs control the bus-transceiver functions. These control signals also allow 4-bit or 16-bit control, depending on the OEB level.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description (continued)

Address and/or data information can be stored using the internal storage latches/flip-flops. The latch-enable (LEB1-LEB4, LEBA, and LEAB1-LEAB4) and clock/clock-enable (CLK/CLKEN) inputs are used to control data storage. When either one of the latch-enable inputs is high, the latch is transparent (clock is a don't care as long as the latch enable is high). When the latch-enable input goes low (providing that the clock does not transit from low to high), the data present at the inputs is latched and remains latched until the latch-enable input is returned high. When the clock enable is low and the corresponding latch enable is low, data can be clocked on the low-to-high transition of the clock. When either the clock enable or the corresponding latch enable is high, the clock is a don't care.

Four select (SEL0, SEL1, CE_SEL0, and CE_SEL1) pins are provided to multiplex data (A port), or to select one of four clock enables (B port). This allows the user the flexibility of controlling one bit at a time.

The B-port outputs, which are designed to sink up to 12 mA, include equivalent $25-\Omega$ series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH162460 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABTH162460 is characterized for operation from -40°C to 85°C.

Function Tables

A-TO-B OUTPUT ENABLE[†]

INP	UTS	OUTPUT
OEB	OEBn	Bn
Н	Н	Z
Н	L	Z
L	Н	Z
L	L	Active

† n = 1, 2, 3, 4

A-TO-B STORAGE (assuming $\overline{OEB} = L$, $\overline{OEBn} = L$)‡

			,	9	,	_,·					
	INPUTS								OUTI	PUTS	
CLKENAB	CE_SEL1	CE_SEL0	CLKAB	LEAB1	LEAB2	LEAB3	LEAB4	B1	B2	В3	В4
Х	Х	Х	H or L	Н	L	L	L	Α	A ₀	A ₀	A ₀
Х	Χ	Χ	H or L	Н	Н	Н	L	Α	Α	Α	A ₀
L	Χ	Χ	L	L	L	L	L	A ₀	A ₀	A_0	A ₀
L	L	L	\uparrow	L	L	L	L	Α	A ₀	A_0	A ₀
L	L	Н	\uparrow	L	L	L	L	A ₀	Α	A_0	A ₀
L	Н	L	\uparrow	L	L	L	L	A ₀	A_0	Α	A ₀
L	Н	Н	\uparrow	L	L	L	L	A ₀	A_0	A_0	Α
Н	Χ	Χ	\uparrow	L	L	L	L	A ₀	A_0	A_0	A ₀

[‡]This table does not cover all the latch-enable cases since they have similar results.



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Function Tables (Continued)

B-TO-A STORAGE (before point P)

			INPUTS	3				Р			
CLKENB	CLKBA	LEB1	LEB2	LEB3	LEB4	SEL1	SEL0	P			
Х	Х	Н	L	L	L	L	L	B1			
Х	X	L	Н	L	L	L	Н	B2			
Х	X	L	L	Н	L	Н	L	В3			
Х	X	L	L	L	Н	Н	Н	В4			
	1								L	L	B1
١,			L	L	L	L	Н	B2			
-		L				Н	L	В3			
						Н	Н	В4			
						L	L	В1 ₀ †			
						L	Н	в2 ₀ †			
		L	L	Н	L	вз ₀ †					
						Н	Н	в4 ₀ †			

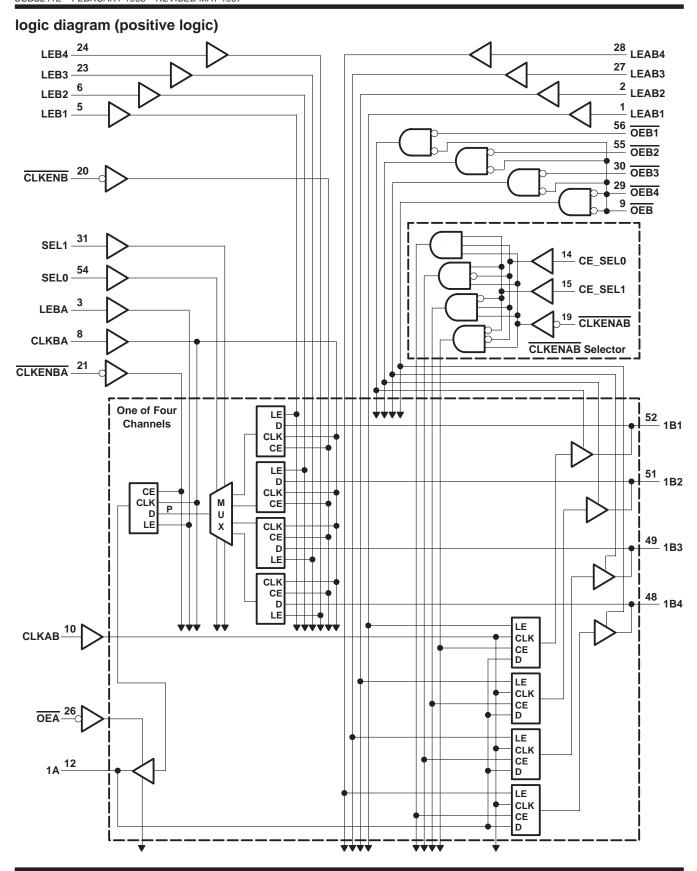
[†] Output level before the indicated steady-state input conditions were established

B-TO-A STORAGE (after point P)

	INPUTS										
CLKENBA	CLKBA	LEBA	Α								
Х	Х	Х	Н	Χ	Z						
Х	Χ	Н	L	L	L						
Х	Χ	Н	L	Н	Н						
Н	Χ	L	L	Χ	A ₀ †						
L	\uparrow	L	L	L	L						
L	\uparrow	L	L	Н	Н						
L	L	L	L	Χ	A ₀ †						

[†] Output level before the indicated steady-state input conditions were established

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

0.5 V to 7 V
0.5 V to 7 V
0.5 V to 5.5 V
96 mA
128 mA
30 mA
–18 mA
–50 mA
74 °C/W
–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

						SN74ABTH162460			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage			4	0.8			0.8	V
VI	Input voltage		0	Ty.	VCC	0		VCC	V
lau	High-level output current	A port		Q	-24			-32	mA
ЮН	rigii-level output current	B port		Ç	-12			-12	IIIA
lo	Low lovel output ourrent	A port		20,	48			64	mA
lOL	Low-level output current	B port	Q	12		12		IIIA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature	•	-55		125	-40		85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ADAMETED	TEOT 001	UDITIONS	SN54	ABTH16	2460	SN74	ABTH16	2460	LINUT
	ARAMETER	lesi coi	NDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
		V _{CC} = 5 V,	I _{OH} = -3 mA	3	3.4		3	3.4		
	A port	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.5	3					
		vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$				2	2.7		
Vон		V _{CC} = 5 V,	I _{OH} = -1 mA	3.8	4.2		3.85			V
	B port		I _{OH} = -1 mA	3.3	3.7		3.35			
	B poit	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	3	3.6		3.1			
			I _{OH} = -12 mA				2.6			
	Aport	V45V	I _{OL} = 24 mA		0.25	0.55				
\/ - .	A port	V _{CC} = 4.5 V	I _{OL} = 64 mA					0.3	0.55	V
VOL	Doom	V 45V	IOL = 8 mA		0.4	0.8		0.4	0.65	V
	B port	V _{CC} = 4.5 V	I _{OL} = 12 mA					0.5	0.8	
V _{hys}					100			100		mV
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	V _I = V _{CC} or GND		±1				±1	
ΙΙ	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$	V _I = V _{CC} or GND		±20				±20	μΑ
la a		$V_{CC} = 5.5 \text{ V}, \qquad V_{I} = 0.8 \text{ V}$		75	2	500	75		500	^
l(hold)	A or B ports	V _{CC} = 4.5 V,	V _I = 2 V	-75	Ċ.	-500	-75		-500	μΑ
	A port	V _{CC} = 5.5 V,	V _O = 2.5 V	-50	<u>3</u> –110	-180	-50		-180	
1 ₀ ‡	B port	V00 - 5 5 V	V _O = 2.5 V	-25	– 55	-90	-25		-90	mA
	Броп	V _{CC} = 5.5 V	V _O = 0	-50	-110	-180	-50		-180	
ICEX	Outputs high	V _{CC} = 5.5 V,	V _O = 5.5 V			50			50	μΑ
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100			±100	μΑ
I _{OZPU} §	3	$V_{CC} = 0$ to 2.1 V, $V_{O} = 0$	0.5 V to 2.7 V, OE = X			±50			±50	μΑ
I _{OZPD} §	3	$V_{CC} = 2.1 \text{ V to } 0, V_{O} =$	0.5 V to 2.7 V, OE = X			±50			±50	μΑ
	Outputs high					1.5		0.7	1.5	
laa	A port low	Voo – 5 5 V Outputs or	200			10		6	10	mA
Icc	B port low	V _{CC} = 5.5 V, Outputs or	Jen			32		18	32	IIIA
	Outputs disabled					1.5		0.7	1.5	
ΔICC¶		$V_{CC} = 5.5 \text{ V}$, One input Other inputs at V_{CC} or 0				1			1	mA
Ci	Control inputs	V _I = 2.5 V or 0.5 V			3.5			3.5		pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			8			8		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This parameter is characterized but not production tested.

[¶]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)(see Figure 1)

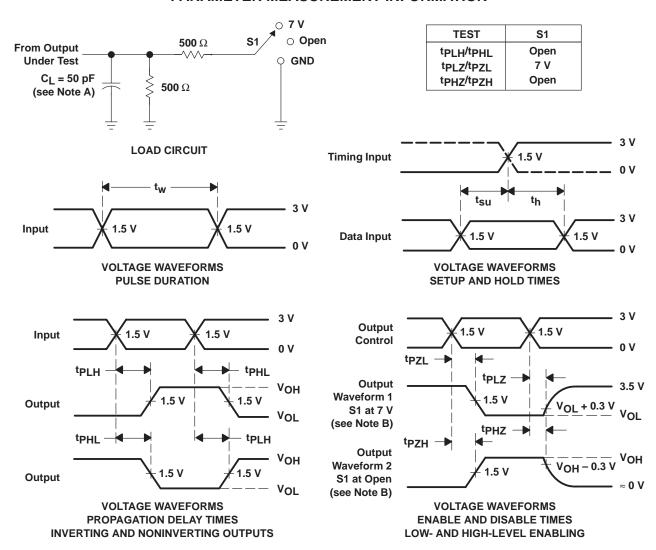
				V _{CC} =	= 5 V, 25°C	SN54ABTH	1162460	SN74ABTH	1162460	UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock freque	ency		0	160	0	160	0	160	MHz	
		CLKAB high or low		3.8		3.8		3.8			
	5.1	CLKBA high or low		4.5		4.5		4.5			
t _W	Pulse duration	LEAB1, 2, 3, or 4 high		2.8		2.8		2.8		ns	
	daration	LEBA high		2.8		2.8		2.8			
		LEB1, 2, 3, or 4 high		3		3		3			
			A bus	2.5		2.5		2.5			
		Before CLKAB↑	CE_SEL0/1	3.2		3.2		3.2			
			CLKENAB	3.2		3.2		3.2			
		Before LEAB1, 2, 3, or 4↓	A bus	3.6		3.6		3.6			
t _{su} Setup time		B bus	3.8		3.8	4	3.8				
	Before CLKBA↑	CLKENB	2.3		2.3	7	2.3				
		CLKENBA	2.5		2.5	4	2.5		ns		
			LEB1, 2, 3, or 4	4.3		4.3		4.3			
			SEL0/1	4.5		4.5		4.5			
		Before LEB1, 2, 3, or 4↓	B bus	3.2		3.2		3.2			
			B bus	4		4		4			
		Before LEBA↓	LEB1, 2, 3, or 4	4.4		4.4		4.4			
			SEL0/1	4.3		4.3		4.3			
			A bus	0.5		0.5		0.5			
		After CLKAB↑	CE_SEL0/1	1.1		1.1		1.1			
			CLKENAB	0.5		0.5		0.5			
		After LEAB1, 2, 3, or 4↓	A bus	1.2		1.2		1.2			
			B bus	1.3		1.3		1.3			
th	Hold time	After CLKBA↑	CLKENB	1		1		1		ns	
		AILEI CLRDAT	CLKENBA	1		1		1			
			SEL0/1	0		0		0			
		After LEB1, 2, 3, or 4↓	B bus	1.5		1.5		1.5			
		After LEBA↓	B bus	0.4		0.4		0.4			
		AIRI LEDAV	SEL0/1	0.1		0.1		0.1			

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		SN54ABTH	1162460	SN74ABTH	1162460	UNIT	
	(INPOT)	(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
f _{max}			160			160		160		MHz	
^t PLH		^	2	3.6	5.9	2	7.1	2	6.5		
^t PHL	В	Α	2	3.5	5.8	2	6.8	2	6.5	ns	
^t PZH	OEA	А	1.5	2.8	4.8	1.5	5.9	1.5	5.6	ns	
t _{PZL}	OEA	^	1.5	2.6	4.8	1.5	5.7	1.5	5.5	115	
^t PHZ	OEA	Α	2	3.8	5.3	2	6	2	5.9	no	
tPLZ	OEA	A	1.5	4	6.1	1.5	7	1.5	6.5	ns	
^t PLH		В	2	3.3	5.5	2	6.5	2	6.2		
^t PHL	Α	Б	2	3.7	5.8	2	6.8	2	6.5	ns	
^t PZH	<u> </u>	В	2	3.9	5.8	2	7.1	2	6.8	ns	
t _{PZL}	OEB	ŌEB	Ь	2	3.7	5.6	2	6.6	1.5	6.3	115
^t PHZ	ŌEB	В	2	4	5.6	2	6.4	2	6.2	no	
tPLZ		Ь	2	3.7	5.2	2	6.1	2	5.8	ns	
^t PZH	OEB1, 2, 3, 4	В	2	3.7	5.8	2	6.8	2	6.6	ns	
tPZL	OEB1, 2, 3, 4	Ь	2	3.5	5.4	2	6.4	2	6.2	115	
^t PHZ	OEB1, 2, 3, 4	В	1.5	3.3	4.8	d .5	5.4	1.5	5.3	no	
tPLZ	OEB1, 2, 3, 4	Ь	1.5	3.1	4.4	1.5	5.1	1.5	4.9	ns	
^t PLH	CLKBA	А	1.5	4.2	6.7	1.5	8.1	1.5	7.4	ns	
^t PHL	CLRBA	A	1.5	4.4	6.9	1.5	8.4	1.5	7.7	115	
^t PLH	CLKAB	В	2	3.5	5.8	2	6.9	2	6.5	ns	
^t PHL	CLNAB	В	2	3.7	6	2	7	2	6.5	115	
^t PLH	LEBA	Α	1.5	3	5.2	1.5	6.3	1.5	5.8	ns	
^t PHL	LLDA	A	1.5	3	5	1.5	6.3	1.5	5.8	115	
^t PLH	LEAB1, 2, 3, 4	В	2	3.4	5.4	2	6.5	2	6.2	ns	
^t PHL	LLAD1, 2, 3, 4		2	3.6	5.7	2	6.3	2	6.2	ns	
^t PLH	LEBA1, 2, 3, 4	А	2	4	6.5	2	7.8	2	7.2	ns	
^t PHL	LLDA1, 2, 3, 4		2	4	6.1	2	7.5	2	6.8	ris	
^t PLH	SEL	А	2	4.1	6.7	2	8.1	2	7.5	ne	
^t PHL	JEL JEL	^	2	3.8	6.2	2	7.3	2	6.9	ns	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

www.ti.com 26-Aug-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABTH162460DGGRE4	ACTIVE	TSSOP	DGG	56	TBD	Call TI	Call TI
74ABTH162460DGGRG4	ACTIVE	TSSOP	DGG	56	TBD	Call TI	Call TI
74ABTH162460DLG4	ACTIVE	SSOP	DL	56	TBD	Call TI	Call TI
74ABTH162460DLRG4	ACTIVE	SSOP	DL	56	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

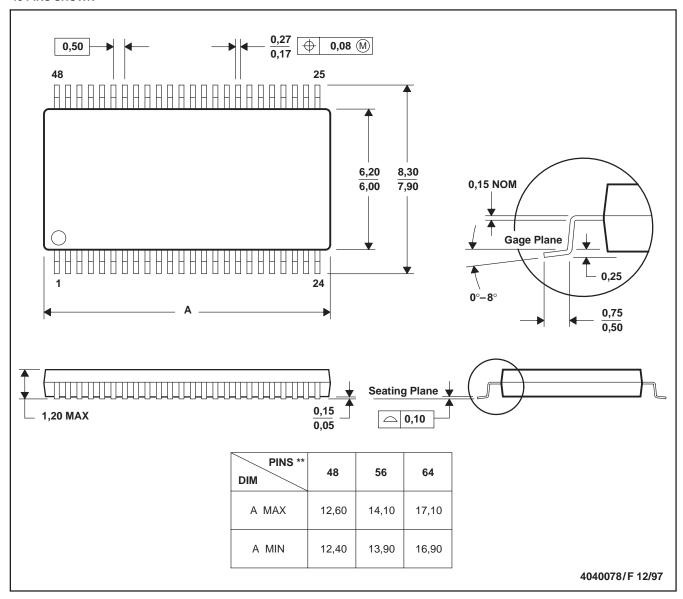
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DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

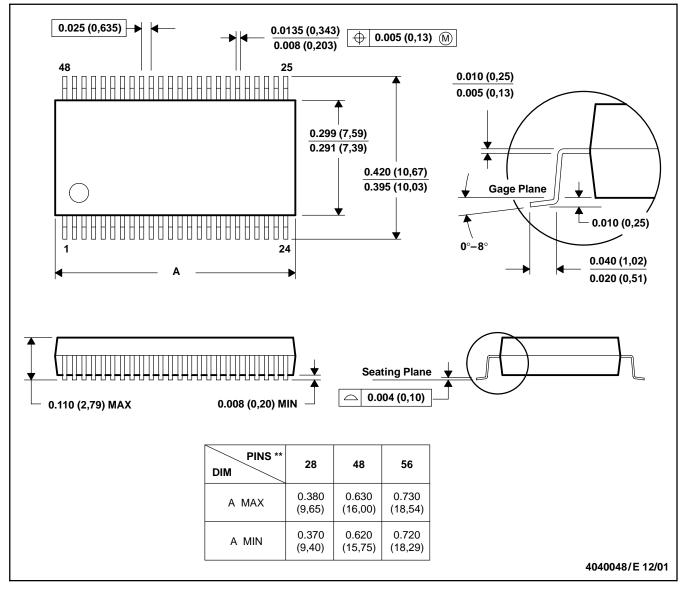
C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

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